



# SOT1176-1

DFN2510A-10: plastic extremely thin small outline package;  
no leads; 10 terminals

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DFN2510A-10
<b>Package type industry code</b>	DFN2510A-10
<b>Package style descriptive code</b>	XSON (extremely thin small outline; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-6-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.4	-	2.5	2.6	mm
E	package width	0.9	-	1	1.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	10	-	



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## 2. Package outline

DFN2510A-10: plastic extremely thin small outline package; no leads; 10 terminals; body 1 x 2.5 x 0.5 mm

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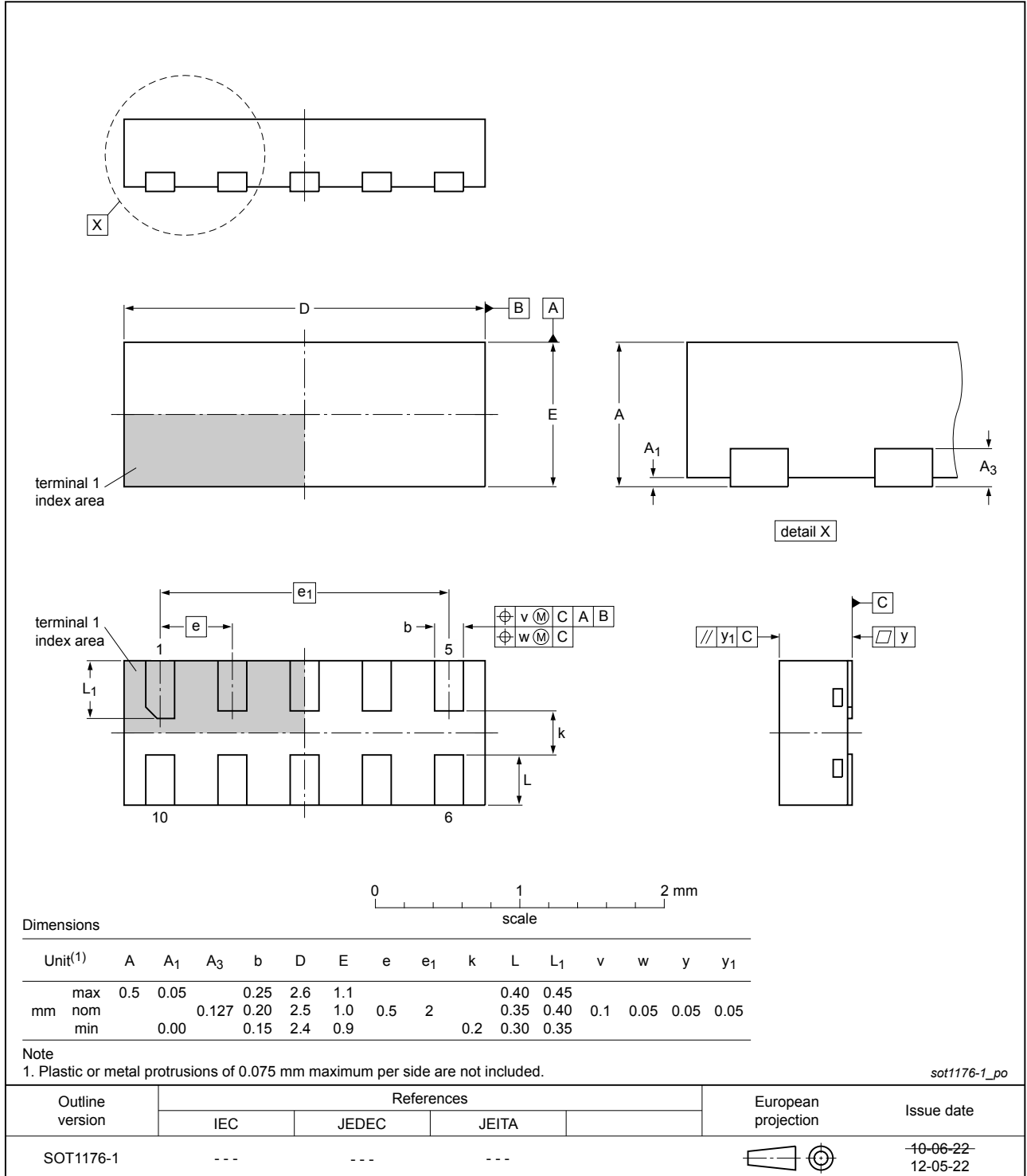


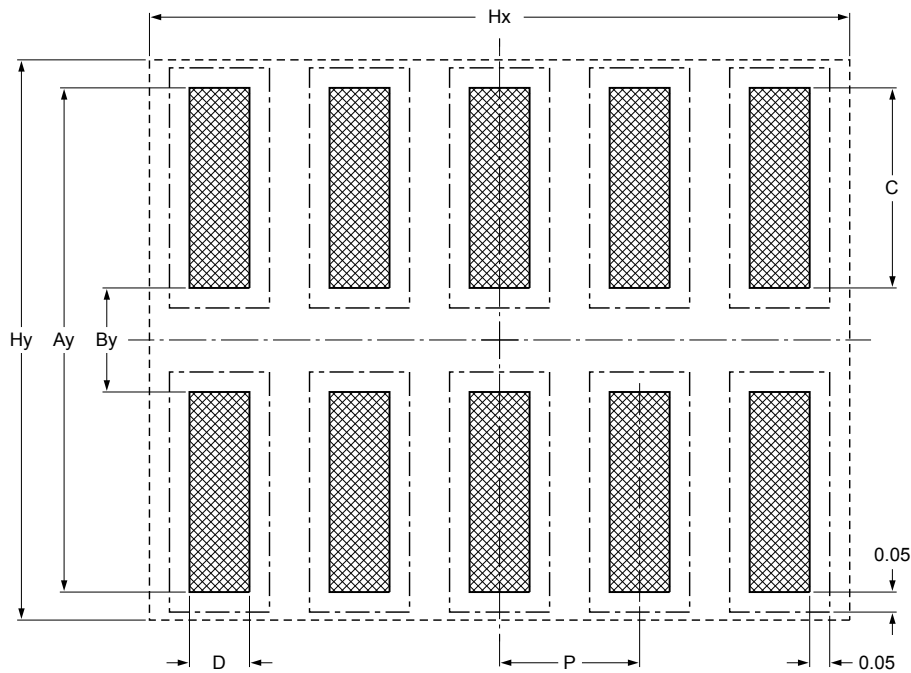
Fig. 1. Package outline DFN2510A-10 (SOT1176-1)

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### 3. Soldering

Footprint information for reflow soldering of DFN2510A-10 package

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Generic footprint pattern  
Refer to the package outline drawing for actual layout

- solder land
- solder paste deposit
- solder land plus solder paste

- occupied area
- solder resist

Dimensions in mm

P	Ay	By	C	D	Hx	Hy
0.5	1.25	0.3	0.475	0.2	2.45	1.5

Remark:  
Stencil of 75  $\mu\text{m}$  is recommended.  
A stencil of 75  $\mu\text{m}$  gives an aspect ratio of 0.77  
With a stencil of 100  $\mu\text{m}$  one will obtain an aspect ratio of 0.58

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Fig. 2. Reflow soldering footprint for DFN2510A-10 (SOT1176-1)

## 4. Legal information

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